



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-04-07
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Emilio Castelli	<b>Representative Title</b>	APG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VN800PSTR-E	RSKU*VNT9ABC	A	SH1A	2016-04-07
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	6x4.9x1.52	8	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th Dec 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RSKU*VNT9ABC					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.464	mg	supplier	die	Silicon (Si)	7440-21-3		3.387	mg	977771	42338
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.024	mg	6928	300
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.023	mg	6640	288
Die				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	577	25
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1443	63
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	6640	288
Leadframe	Copper & its alloys	16.833	mg	supplier	alloy	Copper (Cu)	7440-50-8		16.325	mg	969821	204063
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.384	mg	22812	4800
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.023	mg	1366	288
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.020	mg	1188	250
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.075	mg	4456	938
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	119	25
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	119	25
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.002	mg	119	25
Die attach		1.103	mg	supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.061	mg	55304	763
Die attach				supplier	glue or tape	Bismaleimide resin	Proprietary		0.044	mg	39891	550
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.998	mg	904805	12475
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.199	mg	1000000	2488
encapsulation		58.373	mg	supplier	mold compound	Epoxy Resin	Proprietary		4.271	mg	73167	53388
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		4.271	mg	73167	53388
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		49.319	mg	844894	616488
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.284	mg	4865	3550
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.228	mg	3906	2850